

REMARKS / ARGUMENTS

Claims 1-4 remain pending in this application. Claims 5-31 have been canceled without prejudice or disclaimer. No new claims have been added.

35 U.S.C. §103

Claims 11-31 stand rejected under 35 U.S.C. §102(e) as being anticipated by Oka et al (U.S. Patent No. 6,441,495). Claims 1-5 and 7-31 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Nishizawa et al (U.S. Pub. No. 2002/0030270). Claim 6 stands rejected under 35 U.S.C. §103(a) as being unpatentable over Nishizawa et al in view of Ohie (U.S. Patent No. 6,580,164). These rejections are traversed as follows.

As stated in the previously filed response, the signal interconnection between pads (11A, 11B) of a control chip (10) and pads (21A, 21B) of a memory chip (20), controlled by control chip (10) is contained in the package. The signal interconnection is achieved via a first bonding wire (16, which is a relatively short wire) connecting pads (11A, 11B) of control chip (10) with the inner lead of the first lead (2c, 2d) and third bonding wire (16, which is a relatively long wire) connecting the inner lead of the first lead (2c, 2d) with pads (21A, 21B) of the memory chip (20). Therefore, by randomly selecting a single lead from among a plurality of leads of the lead-frame, signal interconnection between the control chip and the memory chip can

be achieved without requiring plural kinds of lead-frames and/or a special class of control chip having extra bonding pads. Thus, the overall cost of the package can be reduced.

In order to expedite prosecution, claims 5-13 have been canceled without prejudice or disclaimer. Therefore, the only outstanding rejection is that based on Nishizawa et al. Nishizawa et al clearly do not disclose any structure in which a signal terminal (bonding pad) of a memory chip (second chip) and a signal terminal (bonding pad) of a controller chip (first chip) are commonly connected via bonding wires and an inner lead portion of the lead in the resin molded package. In other words, Nishizawa et al clearly do not show that a bonding wire connecting a pad of the second chip and the bonding wire connected to a pad of the first chip are connected to a common lead. Therefore, it is submitted that this rejection should be withdrawn.

Request for Interview

In order to clarify the points raised above, Applicants request the Examiner to conduct an interview with the undersigned. As such, the Examiner is hereby invited to contact the undersigned by telephone in order to arrange an appropriate date and time for such an interview.

Appl. No. 09/964,484
Amendment dated January 10, 2006
Reply to Office Action of July 13, 2005

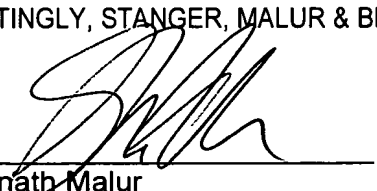
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Conclusion

In view of the foregoing, Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

Respectfully submitted,

MATTINGLY, STANGER, MALUR & BRUNDIDGE, P.C.

By 
Shrinath Malur
Reg. No. 34,663
(703) 684-1120